

Amendments to the Claims:

The following Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (previously presented) A method of forming microstructures on a substrate, the method comprising:

disposing a curable material on a substrate, wherein the curable material comprises a viscosity of less than 12,000 cps;

contacting the curable material with a flexible mold starting at a first end of the substrate and proceeding at a substantially uniform contact speed in a first direction and applying a substantially uniform contact pressure;

forming the curable material, using the mold, into a lattice pattern, wherein the lattice pattern comprises a first set of ribs aligned in the first direction and a second set of ribs aligned in a second direction substantially orthogonal to the first direction, wherein the first set of ribs comprises a pitch of less than 500 μm , the ribs of each set have an average width, and the average width of the second set of ribs to the average width of the first set of ribs has a ratio of at least 1.5;

curing the curable material; and

removing the mold;

and firing the curable material after removing the mold.

2. (cancelled)

3. (currently amended) The method of claim [[2]] 1, wherein the fired curable material is substantially devoid of defects.

4. (original) The method of claim 1, wherein the pitch of the first set of ribs is less than 300 μm .

5. (cancelled)

6. (original) The method of claim 1, wherein a plurality of ribs of the first set of ribs are connected by intervening land regions, and further wherein the intervening land regions comprise a substantially uniform center thickness.
7. (original) The method of claim 1, wherein a plurality of ribs of the second set of ribs are connected by intervening land regions, and further wherein the intervening land regions comprise a substantially uniform center thickness.
8. (original) The method of claim 1, wherein the curable material comprises a ceramic material.
9. (original) The method of claim 1, wherein contacting the curable material comprises unrolling the flexible mold while contacting the curable material starting at the first end of the substrate.
10. (original) The method of claim 9, wherein removing the flexible mold comprises rolling the flexible mold onto a receiving element.
- 11-15. (cancelled)
16. (previously presented) The method of claim 1 wherein the curable material contains a ceramic powder, a curable organic binder, and a diluent.
17. (currently amended) The method of claim 1 wherein the first and second set of ribs have an average width ranging from 20 μm to 50 μm .
18. (previously presented) The method of claim 1 wherein the curable material is disposed on substantially an entire major surface of the substrate.

19. (previously presented) The method of claim 18 wherein the curable material is disposed on the substrate at a thickness that varies by no more than 10%.
20. (previously presented) The method of claim 18 wherein the curable material is disposed on the substrate at a thickness that varies by no more than 5%.
21. (previously presented) The method of claim 18 wherein the curable material is disposed on the substrate at a thickness that varies by no more than 2%.
22. (previously presented) The method of claim 1 wherein the curable material is radiation cured by propagating radiation through the substrate or through the mold.
23. (previously presented) The method of claim 1 wherein the mold is a transparent plastic mold.
24. (previously presented) The method of claim 1 wherein the mold is a flexible polymer sheet having a smooth surface and an opposing microstructured surface.